## **Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the present application.

## **Listing of Claims:**

Claim 1 (currently amended): A wafer holder for semiconductor manufacturing equipment, the wafer holder having a wafer-carrying surface and being trapezoidal in cross-section, such characterized in that the diameter **a** of the wafer holder wafer-carrying surface is not greater than the diameter **b** of the wafer holder surface on its side opposite the wafer-carrying surface, wherein the diameter **b** minus the diameter **a** is less than 35 mm, and wherein the wafer holder is dimensioned to increase in diameter continuously from diameter **a** to diameter **b**.

Claim 2 (previously presented): The wafer holder set forth in claim 1, wherein the diameter  $\boldsymbol{b}$  minus the diameter  $\boldsymbol{a}$  is greater than 50  $\mu$ m and less than 35 mm.

Claim 3 (original): The wafer holder set forth in claim 1, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 4 (original): The wafer holder set forth in claim 2, being a ceramic susceptor interiorly in or superficially on which a resistive heating element is formed.

Claim 5 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 1 is installed.

Claim 6 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 2 is installed.

App. No. 10/709,957 Amendment dated March 7, 2007 Reply to Office action of September 7, 2006

Claim 7 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 3 is installed.

Claim 8 (original): Semiconductor manufacturing equipment wherein the wafer holder set forth in claim 4 is installed.

Claim 9 (new): The wafer holder set forth in claim 1, wherein the diameter **b** minus the diameter **a** is greater than 10 mm and less than 30 mm.

Claims 10-12 (canceled)

Claim 13 (new): The wafer holder set forth in claim 1, wherein the diameter **b** minus the diameter **a** is greater than 1 mm and less than 35 mm.